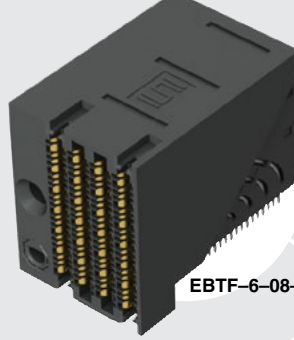


# ExaMAX<sup>®</sup>



EBTF-6-08-2.0-S-RA-1-L-A



EBTF-4-08-2.0-S-RA-1

(2.00 mm) .0787"

# ExaMAX<sup>®</sup> BACKPLANE SYSTEM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?EBTF-RA](http://www.samtec.com?EBTF-RA)

**Insulator Material:** Liquid Crystal Polymer

**Contact Material:** Copper Alloy

**Plating:** Sn or Au over 50 μm (1.27 μm) Ni

**Operating Temp Range:** -55 °C to +105 °C

**Current Rating:** 4.2 A per pin (1 pin powered)

**Contact Wipe:** 2.4 mm

**RoHS Compliant:** Yes

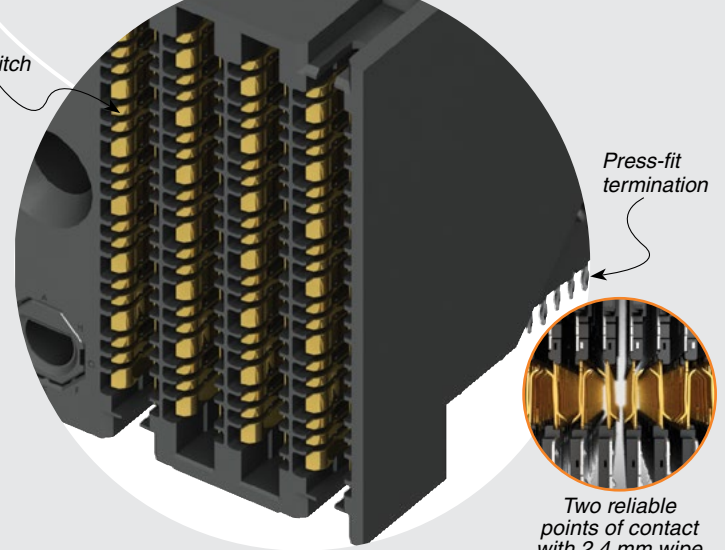
Mates with: EBTM, EBDM

2.00 mm column pitch

Press-fit termination

PAM 4

56 Gbps



Two reliable points of contact with 2.4 mm wipe

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



EBTF

NO. OF PAIRS PER COLUMN

COLUMNS

COLUMN PITCH

-4 = 4 Pairs

-6 = 6 Pairs

-06

-08

-10

-12

(-6 only)

-2.0

= (2.0 mm)

.0787"

## ALSO AVAILABLE (MOQ Required)

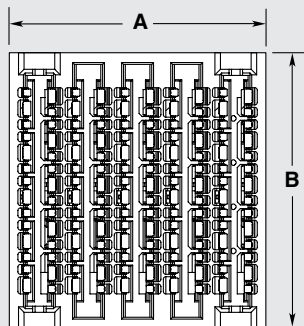
- Staging

## TOOLING

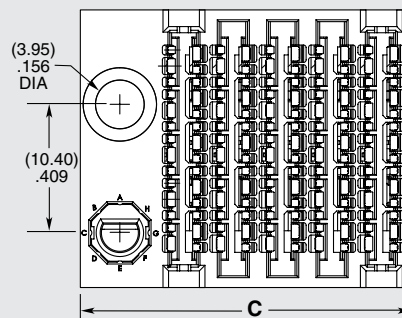
- For press-fit extraction and insertion tool options, visit [www.samtec.com/tooling](http://www.samtec.com/tooling)

NO. OF PAIRS PER COLUMN	B
-4	(22.50) .886
-6	(29.70) 1.169

COLUMNS	A	C
-06	(12.90) .508	(18.85) .742
-08	(16.90) .665	(22.85) .900
-10	(20.90) .823	(26.85) 1.057
-12	(24.90) .980	(30.85) 1.215



NO GUIDANCE SHOWN



WITH GUIDANCE SHOWN

## Notes:

Some lengths, styles and options are non-standard, non-returnable.

ExaMAX<sup>®</sup> is a registered trademark of AFCL.

Due to technical progress, all designs, specifications and components are subject to change without notice.

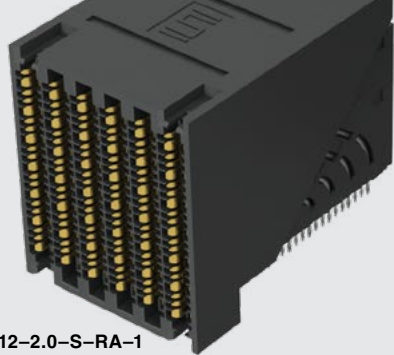
[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.



EBTF-6-6-2.0-S-RA-1-L

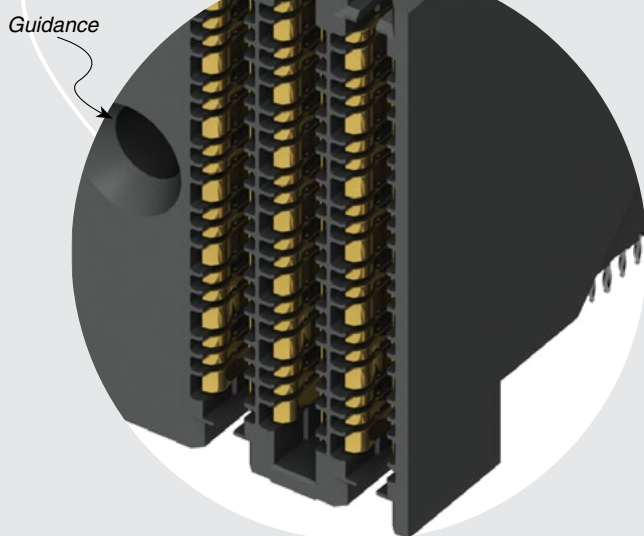


EBTF-6-12-2.0-S-RA-1

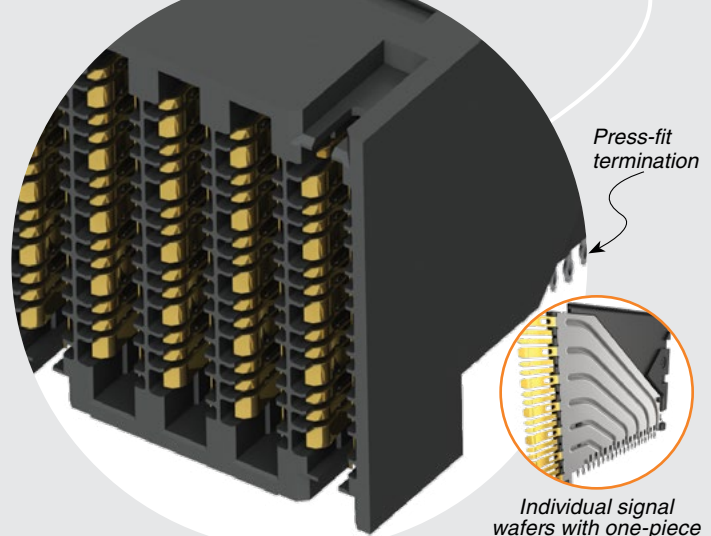


EBTF-4-10-2.0-S-RA-1

**EBTF-RA SERIES**



Guidance



Press-fit termination

Individual signal wafers with one-piece ground plane

**PLATING**

**RA**

**1**

**GUIDANCE**

**KEYING**

**-S**  
= 30 μm (0.76 μm) Gold on contact area,  
Matte Tin on tail

(Leave Blank for no Guidance)

(Only available with -L or -R guidance)

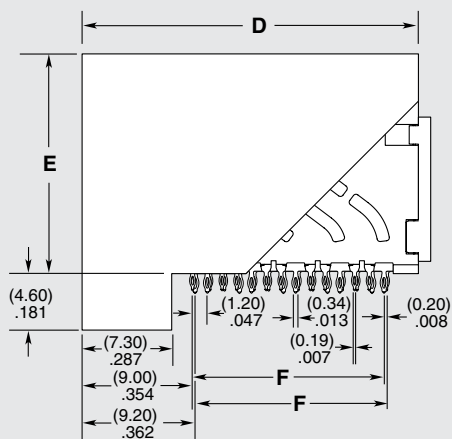
(Leave Blank for no keying)

**-L**  
= Left Guidance

**-A thru -H**  
= Position of flat on Key  
(See table for Key)

**-R**  
= Right Guidance

GUIDANCE	KEYING							
	-A	-B	-C	-D	-E	-F	-G	-H
-R /-L								



EBTF-4-10-2.0-S-RA-1-L-A SHOWN

**APPLICATION**



NO. OF PAIRS PER COLUMN	D	E	F
-4	(28.40) 1.118	(17.90) .705	(15.60) .614
-6	(35.60) 1.402	(25.10) .988	(22.80) .898

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[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

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